

Bill of Materials

TI DESIGNS
Parts# CC3200, TRF7970
TIDC- CC3200-NFC_Card Reader

QTY	Part Reference	Value	Mfr_Name	Mfr_Part_Number	Description
2	C1 C4	10uF	Murata	GRM21BR61A106KE19L	CAP CER 10UF 10V 10% X5R 0805
26	C2 C3 C7 C8 C9 C11 C14 C15 C17 C18 C19 C20 C21 C22 C28 C29 C30 C31 C35 C37 C39 C41 C42 C44 C45 C46	0.1uF	Taiyo Yuden	LMK105BJ104KV-F	CAP CER 0.1UF 10V 10% X5R 0402
1	C5	33000 pF	Samsung	CL05B333KO5NFNC	CAP 33000PF 16V CERAMIC X7R 0402
1	C6	15pF	Murata Electronics North America	GRM1555C1H150JA01D	CAP CER 15PF 50V 5% NP0 0402
2	C10 C12	27pF	Murata Electronics North America	GRM1555C1E270JA01D	CAP CER 27PF 25V 5% NP0 0402
5	C13 C16 C27 C32 C43	10uF	Murata Electronics North America	GRM188R60J106ME47D	CAP CER 10UF 6.3V 20% X5R 0603
2	C23 C24	100uF	TDK Corporation	C3216X5R0J107M160AB	CAP CER 100UF 6.3V 20% X5R 1206
2	C25 C26	10pF	Murata Electronics North America	GRM1555C1H100FA01D	CAP CER 10PF 50V 1% NP0 0402
3	C33 C38 C40	4.7uF	Samsung Electro-Mechanics America, Inc	CL05A475MQ5NRNC	CAP CER 4.7UF 6.3V 20% X5R 0402
2	C34 C36	22uF	Taiyo Yuden	AMK1077BBJ226MAHT	CAP CER 22UF 4V 20% X5R 0603
2	C47 C48	6.2pF	Murata Electronics North America	GRM1555C1H6R2BA01D	CAP CER 6.2PF 50V NP0 0402
1	C49	10pF	AVX Corporation	04025U100CAT2A	CAP CER 10PF 50V NP0 0402
1	C50	1.0pF	Murata Electronics North America	GJM1555C1H1R0BB01D	CAP CER 1PF 50V NP0 0402
2	D1 D6	LED	OSRAM Opto Semiconductors Inc	LY Q976-P1S2-36	LED CHIPLED 587NM YLW 0603 SMD
2	D2 D5	LED	OSRAM Opto Semiconductors Inc	LG Q971-KN-1	LED CHIPLED 570NM GREEN 0603 SMD
1	D3	CD0603-B00340	Bourns Inc	CD0603-B00340	DIODE SCHOTTKY 40V 0.03A 0603
2	D4 D7	LED	OSRAM Opto Semiconductors Inc	LS Q976-NR-1	LED CHIPLED 633NM RED 0603 SMD
1	E1	2.45GHz Ant	Taiyo Yuden	AH316M245001-T	ANT BLUETOOTH W-LAN ZIGBEE WIMAX
1	FL1	2.4GHz Filter	TDK-Epcos	DEA202450BT-1294C1-H	FILTER BANDPASS 2.45GHZ WLAN SMD
1	J1	CONN_MICRO_USB	FCI	10118194-0001LF	CONN USB MICRO B RECPT SMT R/A
13	J14 J15 J16 J17	HEADER_2	TE Connectivity	5-146285-2	CONN HEADR BRKWAY .100 2POS STR
1	J5	HEADER_5	Molex/GC/Waldom Inc.	22-28-4051	CONN HEADER VERT 5 POS .100 TIN
4	J6 J7 J19 J20	HEADER_3	TE Connectivity	5-146282-3	CONN HDR BRKWAY .100 3POS VERT
1	J18	CONN_U_FL	Emerson Network Power Connectivity Johnson	128-0711-201	CONN UMC RCPT STR 50 OHM SMD
2	J22 J23	CONN_RCPT_10x2	Samtec	SSQ-110-03-G-D	CONN RCPT .100" 20POS DUAL GOLD
1	J24	RF SWITCH	Murata	MM8030-2610RJ3	CONN SWG JACK STR 50 OHM SMD
2	L1 L2	FB	Samsung	CIM10U800NC	FERRITE CHIP 80 OHM 600MA 0603 SMD
1	L3	10uH	Taiyo Yuden	CB2518T100K	INDUCTOR POWER 10UH 1007
2	L5 L7	2.2uH	Murata Electronics North America	LQM2HPN2R2MG0L	INDUCTOR 2.2UH 20% 1300MA 1008
1	L6	1uH	Murata	LQM2HPN1R0MJ0L	INDUCTOR POWER 1.0UH 1007
1	L9	3.6nH	Murata Electronics North America	LQP15MN3N6B02D	INDUCTOR 3.6NH 0.1NH 0402
4	Q1 Q3 Q4 Q5	BSS138LT3G	On Semi	BSS138LT3G	MOSFET N-CH 50V 200MA SOT-23
1	Q2	SI2323DS-T1-GE3	Vishay	SI2323DS-T1-GE3	MOSFET P-CH 20V 3.7A SOT23-3
1	R1	100R	Panasonic - ECG	ERJ-2GEJ101X	RES 100 OHM 1/10W 5% 0402 SMD
1	R2	0.1 R	Panasonic	ERJ-S6SFR10V	RES 0.1 OHM 1/4W 1% 0805 SMD
6	R3 R4 R20 R125 R126 R127	270	Panasonic Electronic Components	ERJ-3GEYJ271V	RES 270 OHM 1/10W 5% 0603 SMD
11	R5 R58 R59 R118 R120 R122 R130 R131 R132 R286 R287	100k	Yageo	RC0402JR-07100KL	RES 100K OHM 1/16W 5% 0402 SMD
18	R6 R7 R11 R13 R14 R16 R22 R30 R33 R44 R45 R49 R50 R117 R119 R121 R123 R128	10k	Yageo	RC0402JR-0710KL	RES 10K OHM 1/16W 5% 0402 SMD
2	R8 R9	28	Yageo	RC0402FR-0728RL	RES 28.0 OHM 1/16W 1% 0402 SMD
1	R10	1.5k	Yageo	RC0402FR-071K5L	RES 1.50K OHM 1/16W 1% 0402 SMD
1	R12	2.2K	Panasonic	ERJ-2GEJ222X	RES 2.2K OHM 1/10W 5% 0402 SMD

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15	R15 R19 R25 R26 R28 R29 R34 R35 R36 R40 R41 R46 R52 R53 R56	33	Yageo	RC0402FR-0733RL	RES 33.0 OHM 1/16W 1% 0402 SMD
1	R17	51K	Samsung	RC1005F513CS	RES 51K OHM 1/16W 1% 0402
1	R18	30.1K	Yageo	RC0402FR-0730K1L	RES 30.1K OHM 1/16W 1% 0402 SMD
1	R21	470	Yageo	RC0402FR-07470RL	RES 470 OHM 1/16W 1% 0402 SMD
45	R23 R27 R32 R38 R39 R42 R43 R48 R51 R55 R60 R64 R65 R66 R67 R68 R69 R70 R72 R73 R75 R78 R80 R82 R84 R87 R89 R91 R93 R95 R96 R98 R99 R101 R102 R103 R104 R105 R106 R107 R108 R109 R111 R115 R129	0 R	Panasonic Electronic Components	ERJ-2GE0R00X	RES 0.0 OHM 1/10W JUMP 0402 SMD
14	R24 R31 R63 R71 R74 R76 R77 R83 R85 R92 R94 R97 R110 R285	DNP	DNP	DNP	DO NOT MOUNT
1	R37	DNP	DNP	DNP	DO NOT MOUNT
2	R47 R54	3.3K	Panasonic - ECG	ERJ-2GEJ332X	RES 3.3K OHM 1/10W 5% 0402 SMD
1	R57	270	Yageo	RC0402FR-07270RL	RES 270 OHM 1/16W 1% 0402 SMD
1	R61	2.7k	Yageo	RC0402FR-072K7L	RES 2.70K OHM 1/16W 1% 0402 SMD
2	R116 R124	1k	Yageo	RC0402JR-071KL	RES 1.0K OHM 1/16W 5% 0402 SMD
3	SW1 SW2 SW3	SW TACT	Panasonic	EVQ-11A04M	SWITCH TACTILE SPST-NO 0.02A 15V
1	TP1	TP_1206	TE Connectivity	1625854-4	1206 PROBE PAD
1	U1	TPD2EUSB30	TI	TPD2EUSB30DRTR	IC ESD SOLUTION 2CH SOT3
1	U2	93LC46B-I/MS	Microchip	93LC46B-I/MS	IC SRL EE 1K 64X16 2.5V 8MSOP
1	U3	TPS79601	TEXAS INSTRUMENTS INC	TPS79601DCQR	IC,VREG,LDO,1.2V-5.5V,2.7V-5.5V,--6PIN,SOT-223
1	U5	FT2232D	FUTURE TECHNOLOGY DEVICES INTERNATIONAL LTD	FT2232D	IC, USB UART/FIFO, MPSSE, 12/48MHZ, 48-PIN, LQFP
1	U6	TMP006	Texas Instruments	TMP006A1YZFR	IC SENSOR THERMOPILE 8DSBGA
1	U10	BMA222	Bosch	BMA222E	3-AXIS ACCELEROMETER DIGITAL SMD
2	U11 U12	SN74LVC1T45D	TEXAS INSTRUMENTS INC	SN74LVC1T45DCKR	IC, BUS XCVR, 1-BIT, NON INVERTING, 3-STATE, 6-PIN, SOT-23
1	U13	CC3200	Texas Instruments	CC3200R	ARM M4 MCU with 802.11bg WIFI
1	U15	8M (1M x 8)	Winbond	W25Q80BLSNIG	IC FLASH 8MBIT 75MHZ 8SO
2	U4 U9	SN74LVC125APWR	TEXAS INSTRUMENTS INC	SN74LVC125APWR	IC BUS BUFF TRI-ST QD 14TSSOP
1	U7	SN74LVC126APWR	TEXAS INSTRUMENTS INC	SN74LVC126APWR	IC BUS BUFF TRI-ST QD 14TSSOP
1	U8	TPS61097-33DBVR	TEXAS INSTRUMENTS INC	TPS61097-33DBVR	IC REG BST SYNC 3.3V_1A SOT23-5
1	Y1	CRYSTAL	Epson	CA-301 6.0000M-C:PBFREE	CRYSTAL 6MHZ 18PF THRU
1	Y2	Crystal	Abracon Corporation	ABS07-32.768KHZ-T	CRYSTAL 32.768KHZ 12.5PF SMD
1	Y3	Crystal	Epson	Q24FA20H00396	CRYSTAL 40MHZ 8PF SMD
1		DLP-7970ABP RFID BoosterPack	TRF7970A NFC BoosterPack	DLP Design	DLP-7970ABP

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